

**For immediate release**

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### **John Chrisos Joins NEXX Systems as VP of Customer Operations and Company Occupies New Facility**

**Billerica, MA – January 6, 2004** – NEXX Systems today announced the appointment of John M. Chrisos as vice president of customer operations. John has over 20 years experience in strategic and tactical planning, development and management of multi-million dollar international business operations. Prior to joining NEXX, he served as vice president of worldwide account management and global operations for PRI Automation, having succeeded to this position from two prior VP-level assignments at PRI.

"We are excited to have John join our team," stated Richard Post, CEO of NEXX Systems. "He brings a wealth of semiconductor experience to NEXX at a time when the advanced packaging market and our business are poised to expand rapidly."

Said Chrisos, "NEXX is well positioned to penetrate the advanced packaging market, by developing and manufacturing products which provide high value to customers through improved performance and lower cost of ownership. I am eager to make my contribution to this dynamic team."

In addition, the company relocated to Billerica, MA in late November, occupying 16,000 square feet. The facility has been outfitted with a 10,000 square foot cleanroom demonstration facility and lab space for product development. NEXX is capable of demonstrating sputtered metal films, plasma-deposited dielectric films, and electrodeposited films, along with associated etching and cleaning processes on 150, 200, and 300 mm wafers on Nimbus, Stratus, and Cirrus process equipment. This capability provides the opportunity to develop specific customer processes in the areas of UBM (under bump metallization), backside metal, solder bumps, copper bumps, MRAM shields, various MEMS structures, redistribution layers, and integrated passive devices. NEXX-is uniquely positioned to seamlessly integrate the combination of UBM and electroplating processes as well as other process steps with a complete tool set.

NEXX Systems' products provide established platforms specifically focused on flip chip advanced packaging. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).

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